COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]
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ASSEMBLY VARIANT: [No Variations]

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP30284</th>
<th>REV: B</th>
<th>SUN REV: Not In VersionControl</th>
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<td>TID #:</td>
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<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 8/1/2017 13:14:09</td>
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<td>TEXAS INSTRUMENTS</td>
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